

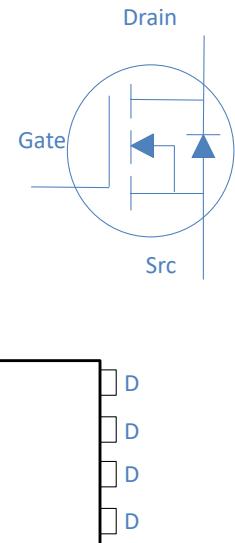
80V N-Ch Power MOSFET
Feature

- ◊ High Speed Power Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

V_{DS}	80	V
$R_{DS(on),typ}$	9.6	$m\Omega$
I_D (Silicon Limited)	34	A

Application

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ DC/DC in Telecoms and Industrial



Part Number	Package	Marking
HGM110N08A	DFN3.3x3.3	M110N08A

Absolute Maximum Ratings at $T_J=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	34	A
		$T_C=100^\circ C$	22	
Drain to Source Voltage	V_{DS}	-	80	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	230	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4mH, T_C=25^\circ C$	45	mJ
Power Dissipation	P_D	$T_C=25^\circ C$	25	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	55	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	5	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	80	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2.0	2.9	4.0	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	-	9.6	11.5	$\text{m}\Omega$
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	29	-	S
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.2	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=40\text{V}, f=1\text{MHz}$	-	1316	-	pF
Output Capacitance	C_{oss}		-	219	-	
Reverse Transfer Capacitance	C_{rss}		-	12	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=40\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	24	-	nC
Gate to Source Charge	Q_{gs}		-	4.5	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	11.5	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	8	-	
Rise time	t_r	$V_{\text{DD}}=40\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega$	-	3	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	23	-	
Fall Time	t_f		-	4	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=40\text{V}, I_F=10\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	36.2	-	ns
Reverse Recovery Charge	Q_{rr}		-	36.2	-	nC

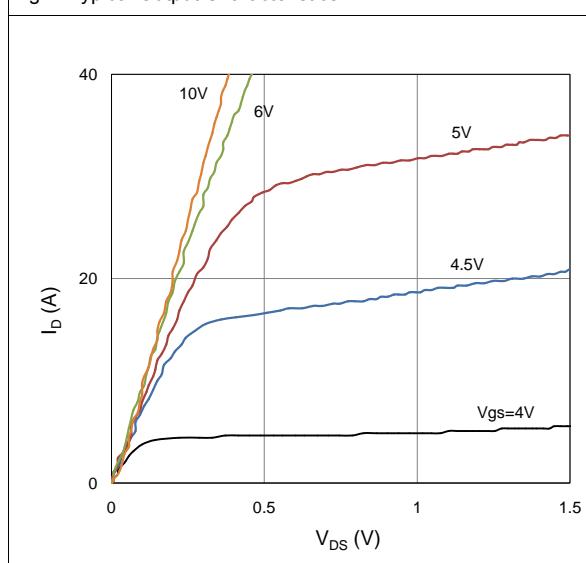
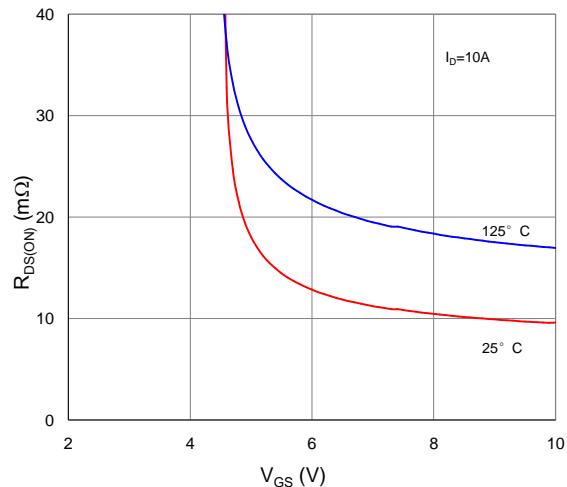
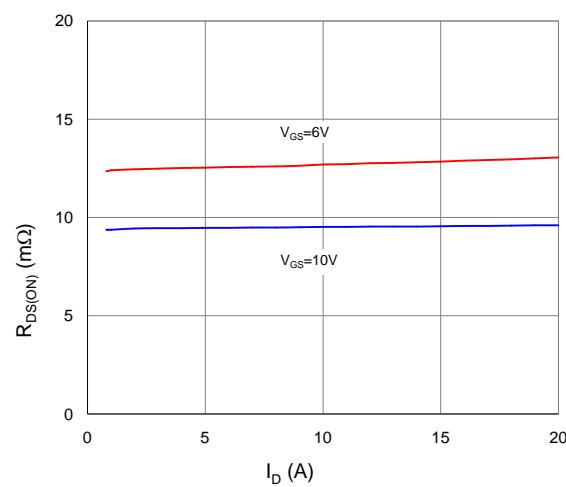
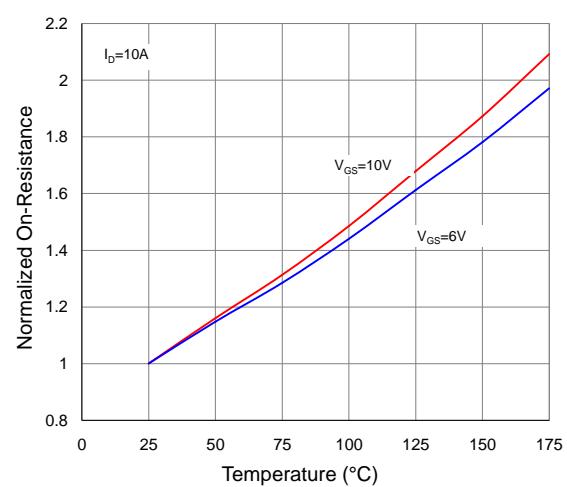
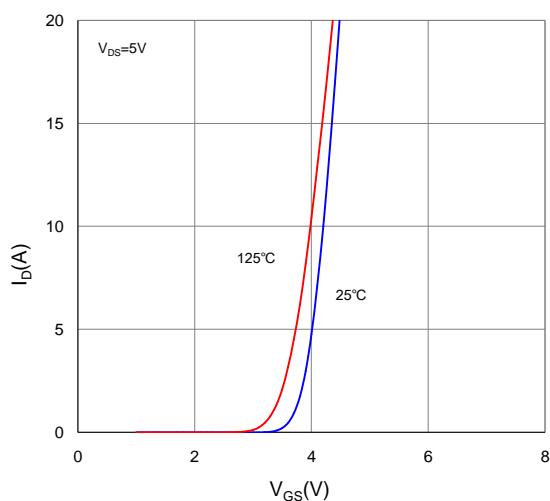
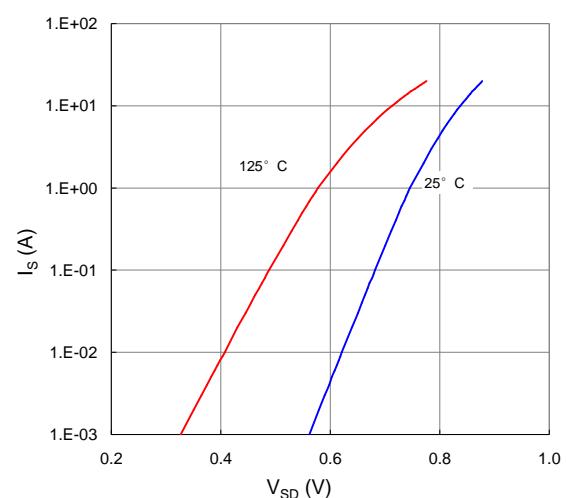
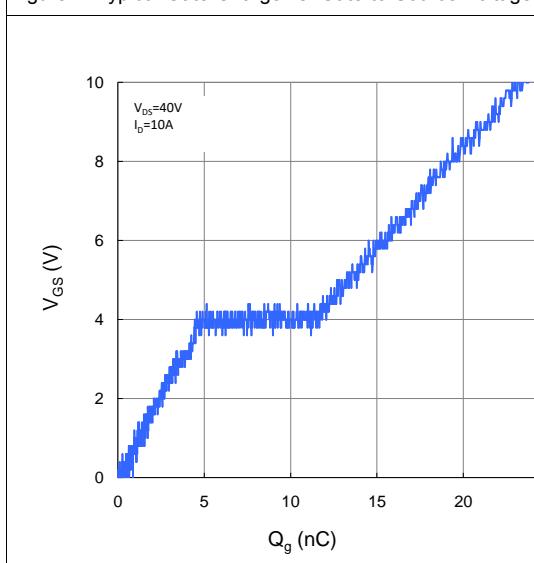
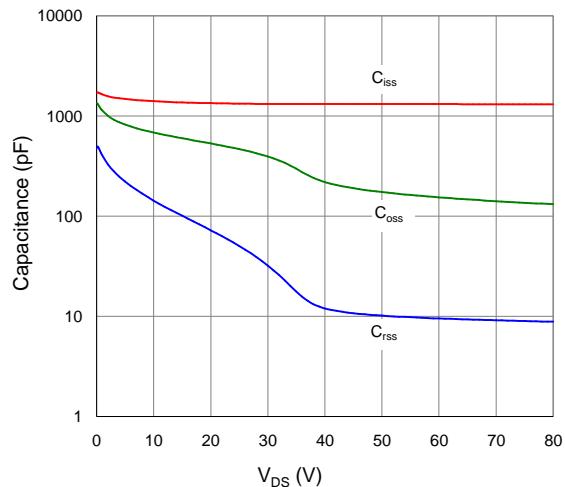
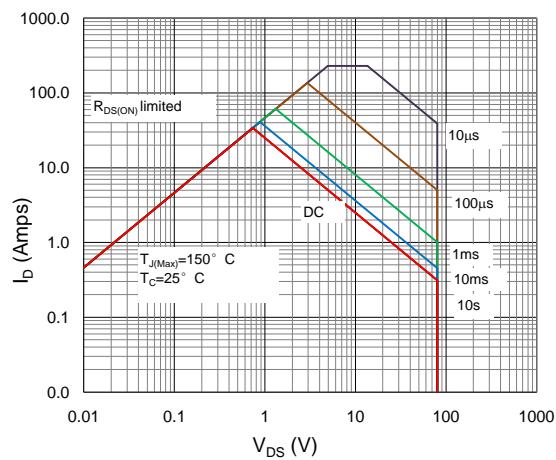
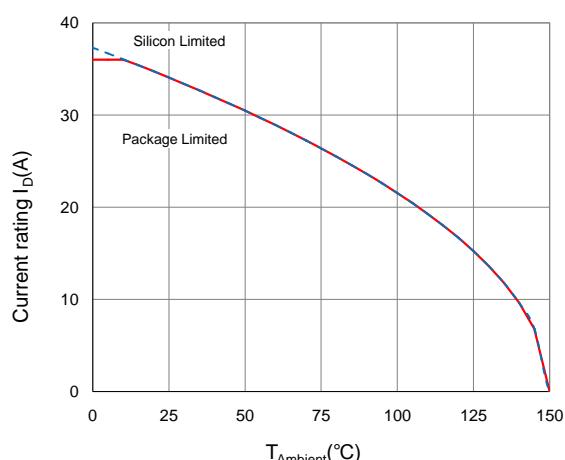
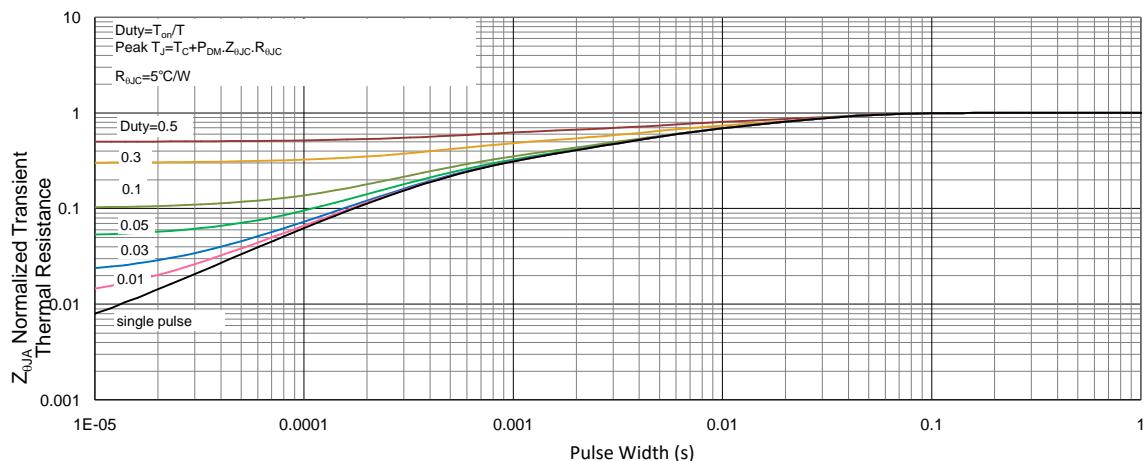
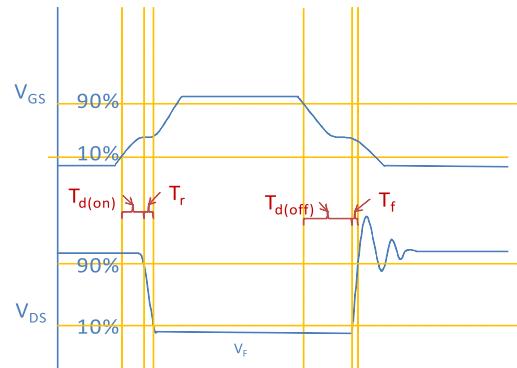
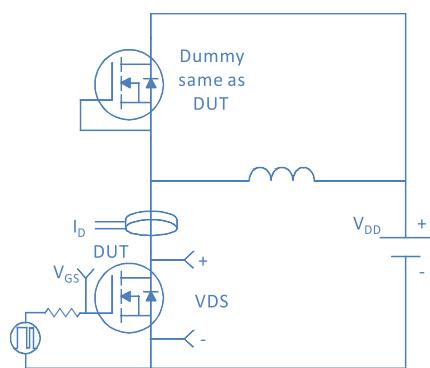
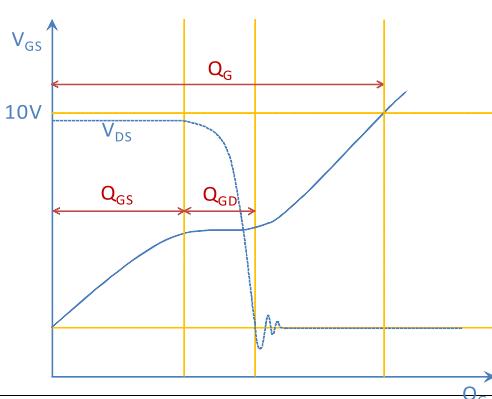
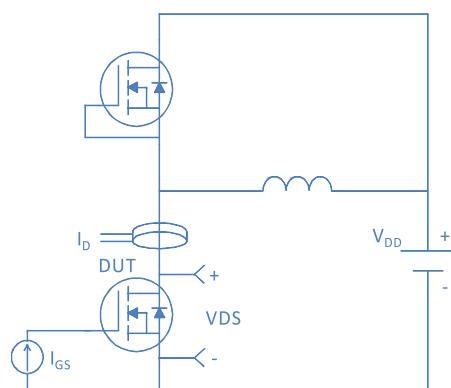
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient


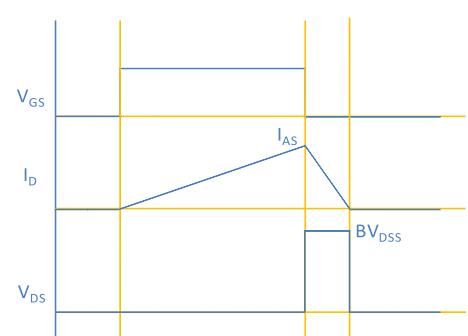
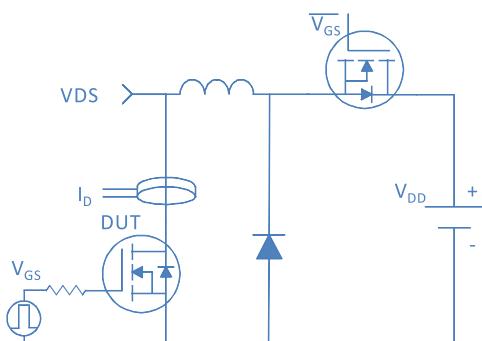
Inductive switching Test



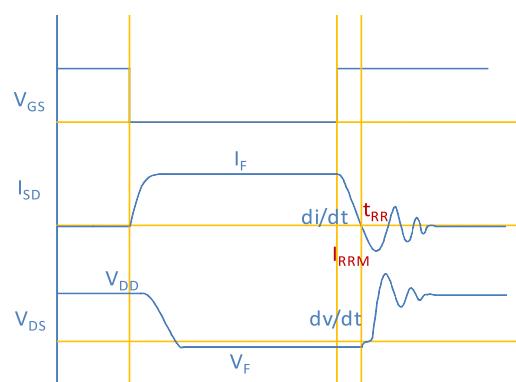
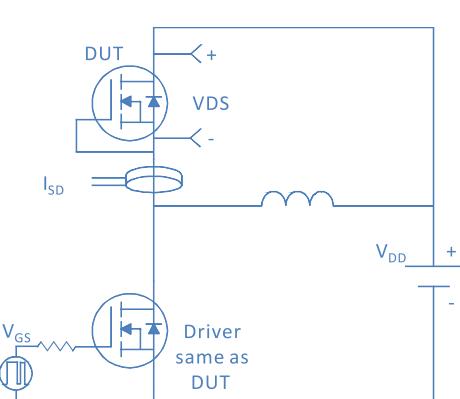
Gate Charge Test

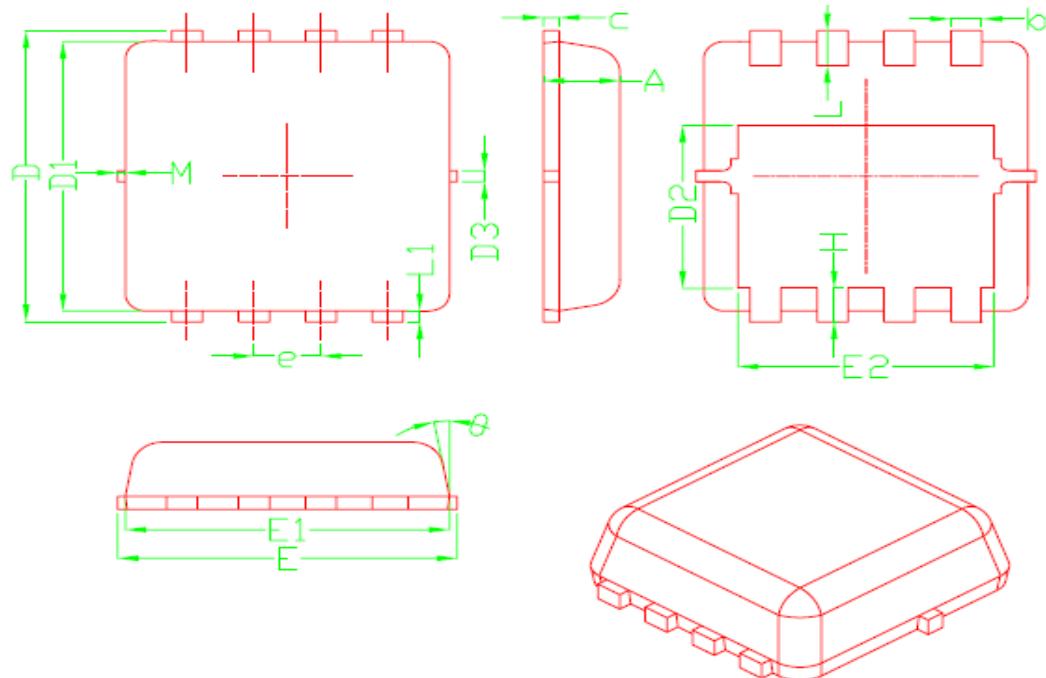


Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



Package Outline
DFN3.3*3.3_P, 8 Leads


SYMBOL	DIMENSIONAL REQUISITS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
θ	---	10°	12°
M	*	*	0.15
* Not specified			